

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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RFM products are now Murata products.

SF1141B

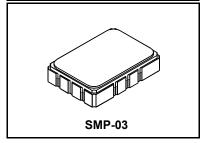
- Designed for SDARS IF Receiver
- · Low Insertion Loss
- 5.0 X 7.0 mm Surface-Mount Case
- Differential Input and Output
- Complies with Directive 2002/95/EC (RoHS)



Absolute Maximum Ratings

Rating	Value	Units			
Maximum Incident Power in Passband	+10	dBm			
Max. DC voltage between any 2 terminals	30	VDC			
Storage Temperature Range -40 to +85		°C			
Max Soldering Profile	265°C	265°C for 10 s			





Electrical Characteristics

Characteristic			Notes	Min	Тур	Max	Units
Nominal Center Frequency		f _C	1	75.000			MHz
Passband	Insertion Loss at fc	IL	'		12.5	16.0	dB
	1dB Passband	BW ₁		±6.35	±7.43		MHz
Fast Amplitude Ripple over fc ±6.35 MHz			1, 2			1.5	dB _{P-P}
	Group Delay Variation over fc ±6.35 MHz	GDV			75	200	ns _{P-P}
Rejection	fc-100 to fc-10.95 and fc+18.8 to fc+100 MHz		1, 2, 3	40	45		dB
	fc+10.95 to fc+18.8 MHz		1, 2, 3	30	36		_ ub
Operating Temporating	erature Range	T _A 1 -40 +85 °C			°C		
Differential Input	and Output Impedance	250 ohms					
Case Style		6 SMP-03 7 x 5 mm Nominal Footprint			orint		
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			O		RFM SF1141	IB YYWWS	

Electrical Connections

Connection	Terminals		
Port 1 Hot	10		
Port 1 Ground Return	1		
Port 2 Hot	5		
Port 2 Ground Return	6		
Case Ground	All Others		



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. NOTES:

Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50Ω and measured with 50Ω network analyzer.

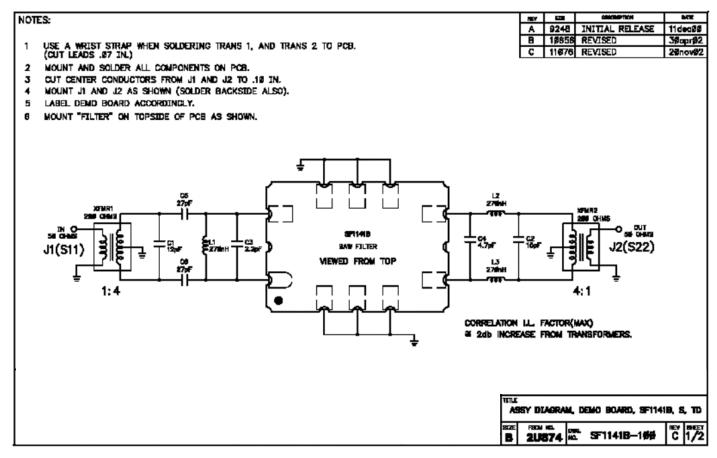
Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.

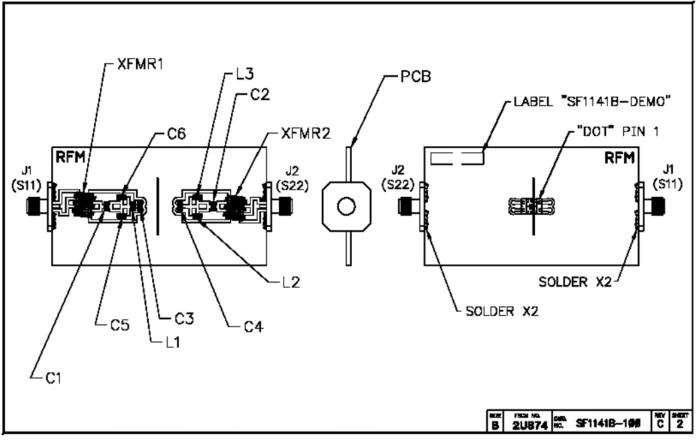
The design, manufacturing process, and specifications of this filter are subject to change.

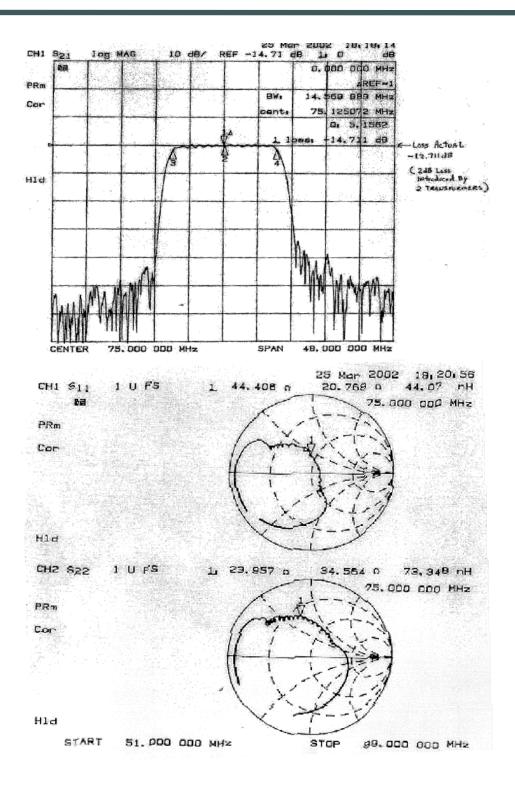
Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2 are that the filter must elevate be investigated in one direction past the size with designs.

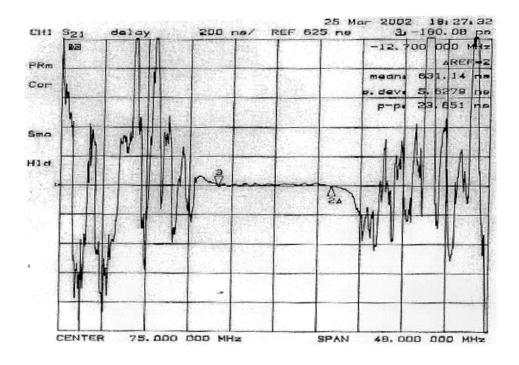
2, so that the filter must always be installed in one direction per the circuit design.

US and international patents may apply.

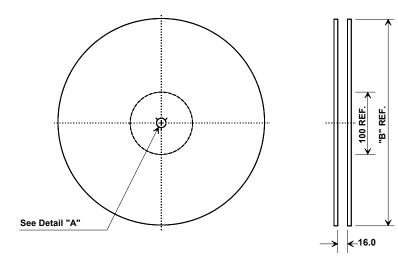




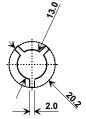




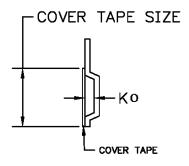
Tape and Reel Specifications



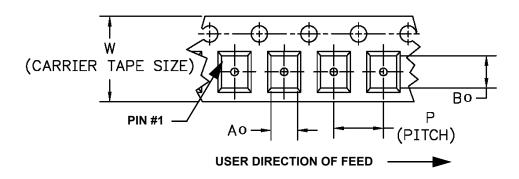
	B " nal Size	Quantity Per Reel	
Inches	millimeters		
7	178	500	
13	330	2000	



COMPONENT ORIENTATION and DIMENSIONS

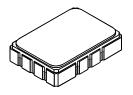


Carrier Tape Dimensions	Tolerance	
Ao	5.5 mm	± 0.1mm
Во	7.5 mm	± 0.1mm
Ко	2.0 mm	± 0.1mm
Pitch	8.0 mm	± 0.1mm
W	16.0 mm	± 0.2mm

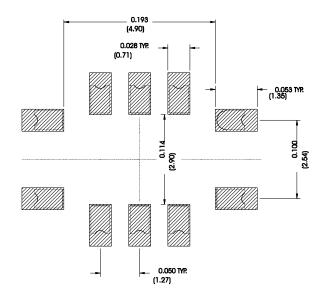


SMP-03 Case

10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



Case Dimensions						
Dimension	mm		Inches			
	Min	Nom	Max	Min	Nom	Max
Α	6.80	7.00	7.20	0.268	0.276	0.283
В	4.80	5.00	5.20	0.189	0.197	0.205
С		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
Н	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
Р	1.14	1.27	1.40	0.045	0.050	0.055

Materials				
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.			
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick			
Body	Al ₂ O ₃ Ceramic			
Pb Free				

Electrical Connections				
	Connection	Terminals		
Port 1	Input or Return	10		
	Return or Input	1		
Port 2	Output or Return	5		
	Return or Output	6		
	Ground	All others		
Single Ended Operation		Return is ground		
Differe	ntial Operation	Return is hot		

